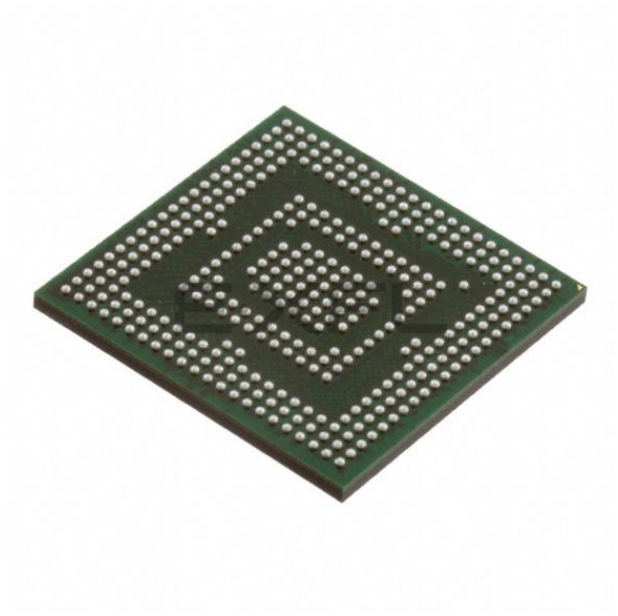

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Floating Point
Interface	CAN, EBI/EMI, Ethernet, DAI, I²C, MMC/SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	450MHz
Non-Volatile Memory	ROM (512kB)
On-Chip RAM	384kB
Voltage - I/O	3.30V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 95°C (TA)
Mounting Type	Surface Mount
Package / Case	349-LFBGA, CSPBGA
Supplier Device Package	349-CSPBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adsp-21583cbcz-4a

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REVISION HISTORY

10/2016—Revision 0: Initial Version

Table 2. Comparison of ADSP-SC58x/ADSP-2158x Processor Features

Processor Feature		ADSP-SC582	ADSP-SC583	ADSP-SC584	ADSP-SC587	ADSP-SC589	ADSP-21583	ADSP-21584	ADSP-21587
ARM Cortex-A5 (MHz, Max)		450	450	450	450	450	N/A	N/A	N/A
ARM Core L1 Cache (I, D kB)		32, 32	32, 32	32, 32	32, 32	32, 32	N/A	N/A	N/A
ARM Core L2 Cache (kB)		256	256	256	256	256	N/A	N/A	N/A
SHARC+ Core1 (MHz, Max)		450	450	450	450	450	450	450	450
SHARC+ Core2 (MHz, Max)		N/A	450	450	450	450	450	450	450
SHARC L1 SRAM/Core (kB)		640	384	640	640	640	384	640	640
System Memory	L2 SRAM (Shared) (kB)	256	256	256	256	256	256	256	256
	L2 ROM (Shared) (kB)	512	512	512	512	512	512	512	512
	DDR3/DDR2/LPDDR1 Controller (16-bit)	1	1	1	2	2	1	1	2
USB 2.0 HS + PHY (Host/Device/OTG)		1	1	1	1	1	N/A	N/A	N/A
USB 2.0 HS + PHY (Host/Device)		N/A	N/A	N/A	1	1	N/A	N/A	N/A
10/100 Std EMAC		N/A	N/A	N/A	1	1	N/A	N/A	N/A
10/100/1000 /AVB EMAC + Timer IEEE 1588		1	1	1	1	1	N/A	N/A	N/A
SDIO/eMMC		N/A	N/A	N/A	1	1	N/A	N/A	N/A
PCIe 2.0 (1 Lane)		N/A	N/A	N/A	N/A	1	N/A	N/A	N/A
RTC		N/A	N/A	N/A	1	1	N/A	N/A	1
GPIO Ports		Port A to E	Port A to E	Port A to E	Port A to G	Port A to G	Port A to E	Port A to E	Port A to G
GPIO + DAI Pins		80 + 28	80 + 28	80 + 28	102 + 40	102 + 40	80 + 28	80 + 28	102 + 40
19 mm × 19 mm Package Options		349-BGA	349-BGA	349-BGA	529-BGA	529-BGA	349-BGA	349-BGA	529-BGA

Table 3. Comparison of ADSP-SC58x/ADSP-2158x Processor Features for Automotive

Processor Feature		ADSP-SC582W	ADSP-SC583W	ADSP-SC584W	ADSP-SC587W	ADSP-21583W	ADSP-21584W
ARM Cortex-A5 (MHz, Max)		450	450	450	450	N/A	N/A
ARM Core L1 Cache (I, D kB)		32, 32	32, 32	32, 32	32, 32	N/A	N/A
ARM Core L2 Cache (kB)		256	256	256	256	N/A	N/A
SHARC+ Core1 (MHz, Max)		450	450	450	450	450	450
SHARC+ Core2 (MHz, Max)		N/A	450	450	450	450	450
SHARC L1 SRAM/Core (kB)		640	384	640	640	384	640
System Memory	L2 SRAM (Shared) (kB)	256	256	256	256	256	256
	L2 ROM (Shared) (kB)	512	512	512	512	512	512
	DDR3/DDR2/LPDDR1 Controller (16-bit)	1	1	1	2	1	1
USB 2.0 HS + PHY (Host/Device/OTG)		1	1	1	1	N/A	N/A
USB 2.0 HS + PHY (Host/Device)		N/A	N/A	N/A	1	N/A	N/A
10/100 Std EMAC		N/A	N/A	N/A	1	N/A	N/A
10/100/1000/AVB EMAC + Timer IEEE 1588		1	1	1	1	N/A	N/A
SDIO/eMMC		N/A	N/A	N/A	1	N/A	N/A
PCIe 2.0 (1 Lane)		N/A	N/A	N/A	N/A	N/A	N/A
MLB 3-Pin/6-Pin		1	1	1	1	1	1
RTC		N/A	N/A	N/A	1	N/A	N/A
GPIO Ports		Port A to E	Port A to E	Port A to E	Port A to G	Port A to E	Port A to E
GPIO + DAI Pins		80 + 28	80 + 28	80 + 28	102 + 40	80 + 28	80 + 28
19 mm × 19 mm Package Options		349-BGA	349-BGA	349-BGA	529-BGA	349-BGA	349-BGA

ARM CORTEX-A5 PROCESSOR

The ARM Cortex-A5 processor (see Figure 2) is a high performance processor with the following features:

- Instruction cache unit (32 Kb) and data L1 cache unit (32 Kb)
- In order pipeline with dynamic branch prediction
- ARM, Thumb, and ThumbEE instruction set support
- ARM TrustZone® security extensions
- Harvard L1 memory system with a memory management unit (MMU)
- ARM v7 debug architecture
- Trace support through an embedded trace macrocell (ETM) interface
- Extension—vector floating-point unit (IEEE 754) with trapless execution
- Extension—media processing engine (MPE) with NEON™ technology
- Extension—Jazelle hardware acceleration

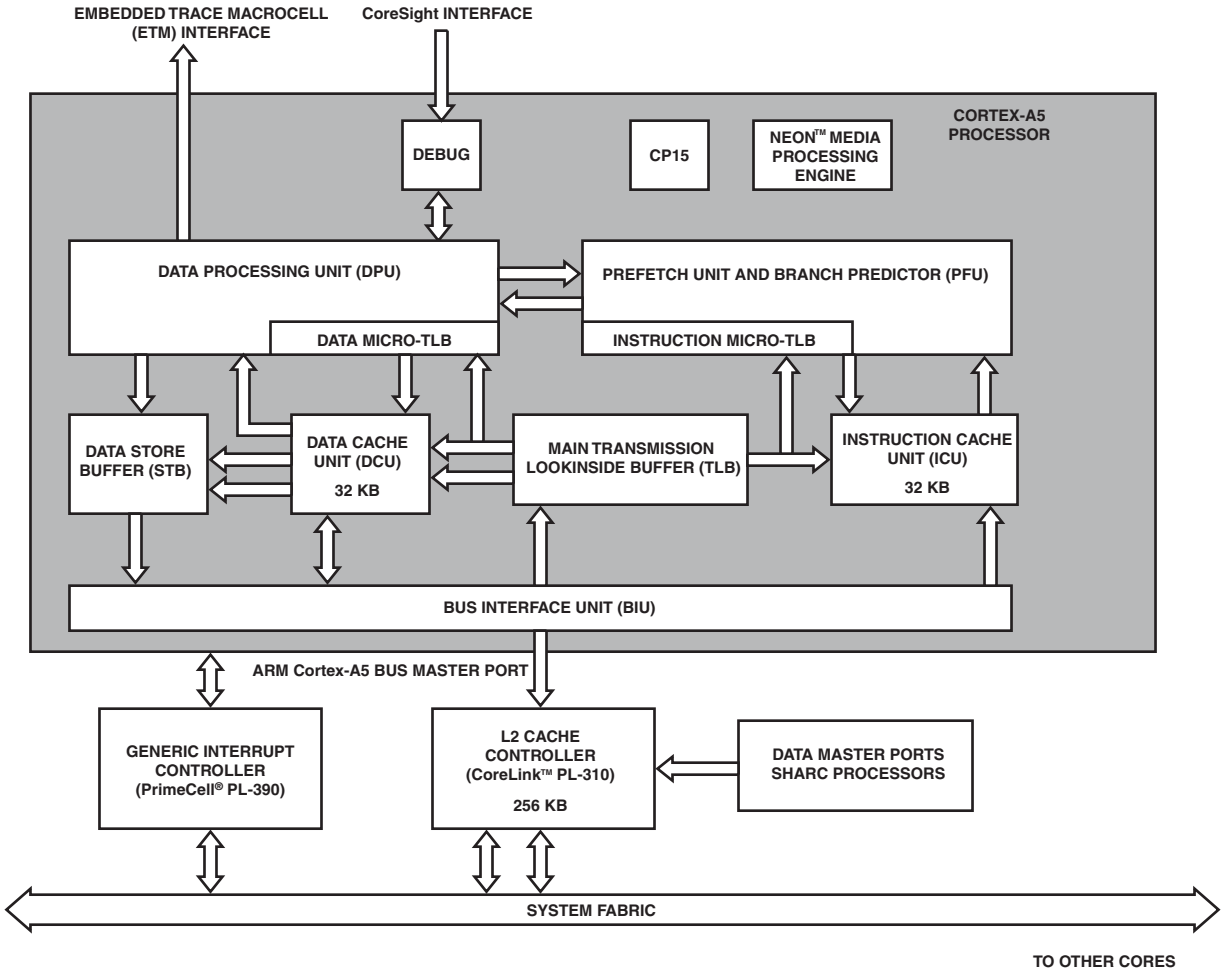

Figure 2. ARM Cortex-A5 Processor Block Diagram

The memory map in Table 4 gives the L1 memory address space and shows multiple L1 memory blocks offering a configurable mix of SRAM and cache.

L1 Master and Slave Ports

Each SHARC+ core has two master and two slave ports to and from the system fabric. One master port fetches instructions. The second master port drives data to the system world. Both slave ports allow conflict free core/direct memory access (DMA) streams to the individual memory blocks. For slave port addresses, refer to the L1 memory address map in Table 4.

L1 On-Chip Memory Bandwidth

The internal memory architecture allows programs to have four accesses at the same time to any of the four blocks, assuming no block conflicts. The total bandwidth is realized using both the DMD and PMD buses.

Instruction and Data Cache

The ADSP-SC58x/ADSP-2158x processors also include a traditional instruction cache (I-cache) and two data caches (D-cache) (PM and DM caches). These caches support one instruction access and two data accesses over the DM and PM buses, per CCLK cycle. The cache controllers automatically manage the configured L1 memory. The system can configure part of the L1 memory for automatic management by the cache controllers. The sizes of these caches are independently configurable from 0 kB to a maximum of 128 kB each. The memory not managed by the cache controllers is directly addressable by the processors. The controllers ensure the data coherence between the two data caches. The caches provide user-controllable features such as full and partial locking, range-bound invalidation, and flushing.

System Event Controller (SEC) Input

The output of the system event controller (SEC) controller is forwarded to the core event controller (CEC) to respond directly to all unmasked system-based interrupts. The SEC also supports nesting including various SEC interrupt channel arbitration options. For all SEC channels, the processor automatically stacks the arithmetic status (ASTATx and ASTATy) registers and mode (MODE1) register in parallel with the interrupt servicing.

Core Memory-Mapped Registers (CMMR)

The core memory-mapped registers control the L1 instruction and data cache, BTB, L2 cache, parity error, system control, debug, and monitor functions.

SHARC+ CORE ARCHITECTURE

The ADSP-SC58x/ADSP-2158x processors are code compatible at the assembly level with the ADSP-2148x, ADSP-2147x, ADSP-2146x, ADSP-2137x, ADSP-2136x, ADSP-2126x, ADSP-2116x, and with the first-generation ADSP-2106x SHARC processors.

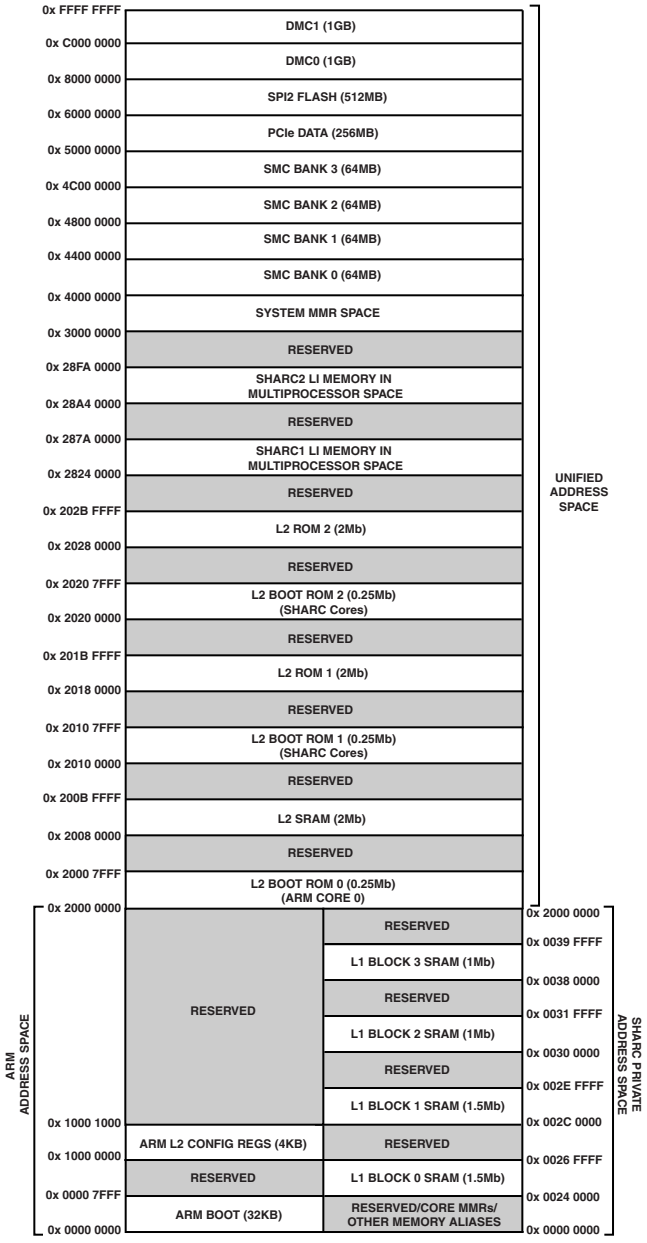

Figure 5. ADSP-SC58x/ADSP-2158x Memory Map

The ADSP-SC58x/ADSP-2158x processors share architectural features with the ADSP-2126x, ADSP-2136x, ADSP-2137x, ADSP-214xx, and ADSP-2116x SIMD SHARC processors, shown in Figure 4 and detailed in the following sections.

SIMD Computational Engine

The SHARC+ core contains two computational processing elements that operate as a single-instruction, multiple data (SIMD) engine.

SYSTEM MEMORY MAP

Table 4. L1 Block 0, Block 1, Block 2, and Block 3 SHARC+ Addressing Memory Map (Private Address Space)

Memory	Long Word (64 Bits)	Extended Precision/ ISA Code (48 Bits)	Normal Word (32 Bits)	Short Word/ VISA Code (16 Bits)	Byte Access (8 Bits)
L1 Block 0 SRAM (1.5 Mb)	0x00048000–0x0004DFFF	0x00090000–0x00097FFF	0x00090000–0x0009BFFF	0x00120000–0x00137FFF	0x00240000–0x0026FFFF
L1 Block 1 SRAM (1.5 Mb)	0x00058000–0x0005DFFF	0x000B0000–0x000B7FFF	0x000B0000–0x000BBFFF	0x00160000–0x00177FFF	0x002C0000–0x002EFFFF
L1 Block 2 SRAM (1 Mb)	0x00060000–0x00063FFF	0x000C0000–0x000C5554	0x000C0000–0x000C7FFF	0x00180000–0x0018FFFF	0x00300000–0x0031FFFF
L1 Block 3 SRAM (1 Mb)	0x00070000–0x00073FFF	0x000E0000–0x000E5554	0x000E0000–0x000E7FFF	0x001C0000–0x001CFFFF	0x00380000–0x0039FFFF

Table 5. L2 Memory Addressing Map

Memory[1]	Byte Address Space ARM Cortex-A5 – Data Access and Instruction Fetch SHARC+ – Data Access	Normal Word Address Space for Data Access SHARC+	Instruction Fetch VISA Address Space SHARC+	Instruction Fetch ISA Address Space SHARC+
L2 Boot ROM0[2]	ARM: 0x00000000–0x00007FFF SHARC+/DMA: 0x20000000–0x20007FFF	0x08000000–0x08001FFF	0x00B80000–0x00B83FFF	0x00580000–0x00581555
L2 RAM (2 Mb)	0x20080000–0x200BFFFF	0x08020000–0x0802FFFF	0x00BA0000–0x00BBFFFF	0x005A0000–0x005AAAAF
L2 Boot ROM1	0x20100000–0x20107FFF	0x08040000–0x08041FFF	0x00B00000–0x00B03FFF	0x00500000–0x00501555
L2 ROM1	0x20180000–0x201BFFFF	0x08060000–0x0806FFFF	0x00B20000–0x00B3FFFF	0x00520000–0x0052AAAF
L2 Boot ROM2[3]	0x20200000–0x20207FFF	0x08080000–0x08081FFF	0x00B40000–0x00B43FFF	0x00540000–0x00541555
L2 ROM2	0x20280000–0x202BFFFF	0x080A0000–0x080AFFFF	0x00B60000–0x00B7FFFF	0x00560000–0x0056AAAF

[1] All L2 RAM/ROM blocks are subdivided into eight banks.
[2] For ADSP-SC58x products, the L2 Boot ROM0 byte address space is 0x 0000 0000–0x 0000 7FFF.
[3] L2 Boot ROM address for ADSP-2158x products.

Table 6. SHARC+ L1 Memory in Multiprocessor Space

		Memory Block	Byte Address Space for ARM Cortex-A5 and SHARC+	Normal Word Address Space for SHARC+
L1 memory of SHARC1 in multiprocessor space	Address via Slave1 Port	Block 0	0x28240000–0x2826FFFF	0x0A090000–0xA09BFFF
		Block 1	0x282C0000–0x282EFFFF	0x0A0B0000–0xA0BBFFF
		Block 2	0x28300000–0x2831FFFF	0x0A0C0000–0x0A0C7FFF
		Block 3	0x28380000–0x2839FFFF	0x0A0E0000–0x0A0E7FFF
	Address via Slave2 Port	Block 0	0x28640000–0x2866FFFF	0x0A190000–0x0A19BFFF
		Block 1	0x286C0000–0x286EFFFF	0x0A1B0000–0x0A1BBFFF
		Block 2	0x28700000–0x2871FFFF	0x0A1C0000–0x0A1C7FFF
		Block 3	0x28780000–0x2879FFFF	0x0A1E0000–0x0A1E7FFF
L1 memory of SHARC2 in multiprocessor space	Address via Slave1 Port	Block 0	0x28A40000–0x28A6FFFF	0x0A290000–0x0A29BFFF
		Block 1	0x28AC0000–0x28AEFFFF	0x0A2B0000–0x0A2BBFFF
		Block 2	0x28B00000–0x28B1FFFF	0x0A2C0000–0x0A2C7FFF
		Block 3	0x28B80000–0x28B9FFFF	0x0A2E0000–0x0A2E7FFF
	Address via Slave2 Port	Block 0	0x28E40000–0x28E6FFFF	0x0A390000–0x0A39BFFF
		Block 1	0x28EC0000–0x28EEFFFF	0x0A3B0000–0x0A3BBFFF
		Block 2	0x28F00000–0x28F1FFFF	0x0A3C0000–0x0A3C7FFF
		Block 3	0x28F80000–0x28F9FFFF	0x0A3E0000–0x0A3E7FFF

349-BALL CSP_BGA SIGNAL DESCRIPTIONS

The processor pin definitions are shown in Table 12 for the 349-ball CSP_BGA package. The columns in this table provide the following information:

- The signal name column includes the signal name for every pin and the GPIO multiplexed pin function, where applicable.
- The description column provides a descriptive name for each signal.
- The port column shows whether or not a signal is multiplexed with other signals on a general-purpose I/O port pin.
- The pin name column identifies the name of the package pin (at power on reset) on which the signal is located (if a single function pin) or is multiplexed (if a general-purpose I/O pin).
- The DAI pins and their associated signal routing units (SRUs) connect inputs and outputs of the DAI peripherals (SPORT, ASRC, S/PDIF, and PCG). See the Digital Audio Interface (DAI) chapter of the ADSP-SC58x/ADSP-2158x SHARC+ Processor Hardware Reference for complete information on the use of the DAI and SRUs.

Table 12. ADSP-SC58x/ADSP-2158x 349-Ball CSP_BGA Signal Descriptions

Signal Name	Description	Port	Pin Name
ACM0_A0	ACM0 ADC Control Signals	C	PC_13
ACM0_A1	ACM0 ADC Control Signals	C	PC_14
ACM0_A2	ACM0 ADC Control Signals	C	PC_15
ACM0_A3	ACM0 ADC Control Signals	D	PD_00
ACM0_A4	ACM0 ADC Control Signals	D	PD_01
ACM0_T0	ACM0 External Trigger n	C	PC_12
C1_FLG0	SHARC Core 1 Flag Pin	E	PE_01
C1_FLG1	SHARC Core 1 Flag Pin	E	PE_03
C1_FLG2	SHARC Core 1 Flag Pin	E	PE_05
C1_FLG3	SHARC Core 1 Flag Pin	E	PE_07
C2_FLG0	SHARC Core 2 Flag Pin	E	PE_02
C2_FLG1	SHARC Core 2 Flag Pin	E	PE_04
C2_FLG2	SHARC Core 2 Flag Pin	E	PE_06
C2_FLG3	SHARC Core 2 Flag Pin	E	PE_08
CAN0_RX	CAN0 Receive	C	PC_07
CAN0_TX	CAN0 Transmit	C	PC_08
CAN1_RX	CAN1 Receive	B	PB_10
CAN1_TX	CAN1 Transmit	B	PB_09
CNT0_DG	CNT0 Count Down and Gate	B	PB_14
CNT0_UD	CNT0 Count Up and Direction	B	PB_12
CNT0_ZM	CNT0 Count Zero Marker	B	PB_11
DAI0_PIN01	DAI0 Pin 1	Not Muxed	DAI0_PIN01
DAI0_PIN02	DAI0 Pin 2	Not Muxed	DAI0_PIN02
DAI0_PIN03	DAI0 Pin 3	Not Muxed	DAI0_PIN03
DAI0_PIN04	DAI0 Pin 4	Not Muxed	DAI0_PIN04
DAI0_PIN05	DAI0 Pin 5	Not Muxed	DAI0_PIN05
DAI0_PIN06	DAI0 Pin 6	Not Muxed	DAI0_PIN06
DAI0_PIN07	DAI0 Pin 7	Not Muxed	DAI0_PIN07
DAI0_PIN08	DAI0 Pin 8	Not Muxed	DAI0_PIN08
DAI0_PIN09	DAI0 Pin 9	Not Muxed	DAI0_PIN09
DAI0_PIN10	DAI0 Pin 10	Not Muxed	DAI0_PIN10
DAI0_PIN11	DAI0 Pin 11	Not Muxed	DAI0_PIN11
DAI0_PIN12	DAI0 Pin 12	Not Muxed	DAI0_PIN12
DAI0_PIN19	DAI0 Pin 19	Not Muxed	DAI0_PIN19
DAI0_PIN20	DAI0 Pin 20	Not Muxed	DAI0_PIN20

Table 19. ADSP-SC58x/ADSP-2158x 529-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
DMC1_BA2	DMC1 Bank Address 2	Not Muxed	DMC1_BA2
$\overline{\text{DMC1\_CAS}}$	DMC1 Column Address Strobe	Not Muxed	$\overline{\text{DMC1\_CAS}}$
DMC1_CK	DMC1 Clock	Not Muxed	DMC1_CK
DMC1_CKE	DMC1 Clock enable	Not Muxed	DMC1_CKE
$\overline{\text{DMC1\_CK}}$	DMC1 Clock (complement)	Not Muxed	$\overline{\text{DMC1\_CK}}$
$\overline{\text{DMC1\_CS0}}$	DMC1 Chip Select 0	Not Muxed	$\overline{\text{DMC1\_CS0}}$
DMC1_DQ00	DMC1 Data 0	Not Muxed	DMC1_DQ00
DMC1_DQ01	DMC1 Data 1	Not Muxed	DMC1_DQ01
DMC1_DQ02	DMC1 Data 2	Not Muxed	DMC1_DQ02
DMC1_DQ03	DMC1 Data 3	Not Muxed	DMC1_DQ03
DMC1_DQ04	DMC1 Data 4	Not Muxed	DMC1_DQ04
DMC1_DQ05	DMC1 Data 5	Not Muxed	DMC1_DQ05
DMC1_DQ06	DMC1 Data 6	Not Muxed	DMC1_DQ06
DMC1_DQ07	DMC1 Data 7	Not Muxed	DMC1_DQ07
DMC1_DQ08	DMC1 Data 8	Not Muxed	DMC1_DQ08
DMC1_DQ09	DMC1 Data 9	Not Muxed	DMC1_DQ09
DMC1_DQ10	DMC1 Data 10	Not Muxed	DMC1_DQ10
DMC1_DQ11	DMC1 Data 11	Not Muxed	DMC1_DQ11
DMC1_DQ12	DMC1 Data 12	Not Muxed	DMC1_DQ12
DMC1_DQ13	DMC1 Data 13	Not Muxed	DMC1_DQ13
DMC1_DQ14	DMC1 Data 14	Not Muxed	DMC1_DQ14
DMC1_DQ15	DMC1 Data 15	Not Muxed	DMC1_DQ15
DMC1_LDM	DMC1 Data Mask for Lower Byte	Not Muxed	DMC1_LDM
DMC1_LDQS	DMC1 Data Strobe for Lower Byte	Not Muxed	DMC1_LDQS
$\overline{\text{DMC1\_LDQS}}$	DMC1 Data Strobe for Lower Byte (complement)	Not Muxed	$\overline{\text{DMC1\_LDQS}}$
DMC1_ODT	DMC1 On-die termination	Not Muxed	DMC1_ODT
$\overline{\text{DMC1\_RAS}}$	DMC1 Row Address Strobe	Not Muxed	$\overline{\text{DMC1\_RAS}}$
$\overline{\text{DMC1\_RESET}}$	DMC1 Reset (DDR3 only)	Not Muxed	$\overline{\text{DMC1\_RESET}}$
DMC1_RZQ	DMC1 External calibration resistor connection	Not Muxed	DMC1_RZQ
DMC1_UDM	DMC1 Data Mask for Upper Byte	Not Muxed	DMC1_UDM
DMC1_UDQS	DMC1 Data Strobe for Upper Byte	Not Muxed	DMC1_UDQS
$\overline{\text{DMC1\_UDQS}}$	DMC1 Data Strobe for Upper Byte (complement)	Not Muxed	$\overline{\text{DMC1\_UDQS}}$
DMC1_VREF	DMC1 Voltage Reference	Not Muxed	DMC1_VREF
$\overline{\text{DMC1\_WE}}$	DMC1 Write Enable	Not Muxed	$\overline{\text{DMC1\_WE}}$
ETH0_CRS	ETH0 Carrier Sense/RMII Receive Data Valid	A	PA_07
ETH0_MDC	ETH0 Management Channel Clock	A	PA_02
ETH0_MDIO	ETH0 Management Channel Serial Data	A	PA_03
ETH0_PTPAUXIN0	ETH0 PTP Auxiliary Trigger Input 0	B	PB_03
ETH0_PTPAUXIN1	ETH0 PTP Auxiliary Trigger Input 1	B	PB_04
ETH0_PTPAUXIN2	ETH0 PTP Auxiliary Trigger Input 2	B	PB_05
ETH0_PTPAUXIN3	ETH0 PTP Auxiliary Trigger Input 3	B	PB_06
ETH0_PTPCLKIN0	ETH0 PTP Clock Input 0	B	PB_02
ETH0_PTPPPS0	ETH0 PTP Pulse-Per-Second Output 0	B	PB_01
ETH0_PTPPPS1	ETH0 PTP Pulse-Per-Second Output 1	B	PB_00
ETH0_PTPPPS2	ETH0 PTP Pulse-Per-Second Output 2	A	PA_15
ETH0_PTPPPS3	ETH0 PTP Pulse-Per-Second Output 3	A	PA_14
ETH0_RXCLK_REFCLK	ETH0 RXCLK (GigE) or REFCLK (10/100)	A	PA_06
ETH0_RXCTL_CRS	ETH0 RXCTL (GigE) or CRS (10/100)	A	PA_07

Table 24. Signal Multiplexing for Port E (Continued)

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PE_03	PPI0_CLK	SPI0_SEL7	SPI2_SEL2	C1_FLG1	
PE_04	PPI0_D08	PWM2_DH	SPI2_SEL3	C2_FLG1	
PE_05	PPI0_D07	PWM2_SYNC	SPI2_SEL4	C1_FLG2	
PE_06	PPI0_D06		SPI2_SEL5	C2_FLG2	
PE_07	PPI0_D05		SPI1_SEL2	C1_FLG3	
PE_08	PPI0_D04	SPI1_SEL5	SPI1_RDY	C2_FLG3	
PE_09	PPI0_D03	PWM0_SYNC	TM0_TMR0	SMC0_D03	
PE_10	PPI0_D02	PWM2_DL	UART2_RTS	SMC0_D02	
PE_11	PPI0_D01	SPI1_SEL3	UART2_CTS	SMC0_D01	SPI1_SS
PE_12	PPI0_D00	SPI1_SEL4	SPI2_RDY	SMC0_D00	
PE_13	SPI1_CLK		PPI0_D20	SMC0_AMS1	
PE_14	SPI1_MISO		PPI0_D21	SMC0_ABE0	
PE_15	SPI1_MOSI		PPI0_D22	SMC0_ABE1	

Table 25. Signal Multiplexing for Port F

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PF_00	TM0_TMR6	SPI1_SEL6			
PF_01	TM0_TMR7	SPI1_SEL7			
PF_02	MSI0_D0	HADC0_EOC_DOUT			
PF_03	MSI0_D1	HADC0_MUX2			
PF_04	MSI0_D2	HADC0_MUX1			
PF_05	MSI0_D3	HADC0_MUX0			
PF_06	MSI0_D4	PWM2_AL			
PF_07	MSI0_D5	PWM2_AH			
PF_08	MSI0_D6	PWM2_BL			
PF_09	MSI0_D7	PWM2_BH			
PF_10	MSI0_CMD				
PF_11	MSI0_CLK				
PF_12	MSI0_CD				
PF_13	ETH1_CRS	TRACE0_D08	TRACE0_D00	MSI0_INT	
PF_14	ETH1_MDC	TRACE0_D09	TRACE0_D01		
PF_15	ETH1_MDIO	TRACE0_D10	TRACE0_D02		

Table 26. Signal Multiplexing for Port G

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PG_00	ETH1_REFCLK	TRACE0_CLK			
PG_01	ETH1_TXEN	TRACE0_D11	TRACE0_D03		
PG_02	ETH1_TXD0	TRACE0_D12	TRACE0_D04		
PG_03	ETH1_TXD1	TRACE0_D13	TRACE0_D05		
PG_04	ETH1_RXD0	TRACE0_D14	TRACE0_D06		
PG_05	ETH1_RXD1	TRACE0_D15	TRACE0_D07		

Table 27. ADSP-SC58x/ADSP-2158x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Power Domain	Description and Notes
HADC0_VREFN	s	NA	none	none	none	VDD_HADC	Desc: HADC0 Ground Reference for ADC Notes: No notes
HADC0_VREFP	s	NA	none	none	none	VDD_HADC	Desc: HADC0 External Reference for ADC Notes: No notes
JTG_TCK	Input		PullUp	none	none	VDD_EXT	Desc: JTAG Clock Notes: No notes
JTG_TDI	Input		PullUp	none	none	VDD_EXT	Desc: JTAG Serial Data In Notes: No notes
JTG_TDO	Output	A	none	none	none	VDD_EXT	Desc: JTAG Serial Data Out Notes: No notes
JTG_TMS	InOut	A	PullUp	none	none	VDD_EXT	Desc: JTAG Mode Select Notes: No notes
$\overline{\text{JTG\_TRST}}$	Input		PullDown	none	none	VDD_EXT	Desc: JTAG Reset Notes: No notes
MLB0_CLKN	Input	NA	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Clock (-) Notes: No notes
MLB0_CLKP	Input	NA	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Clock (+) Notes: No notes
MLB0_DATN	InOut	I	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Data (-) Notes: No notes
MLB0_DATP	InOut	I	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Data (+) Notes: No notes
MLB0_SIGN	InOut	I	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Signal (-) Notes: No notes
MLB0_SIGP	InOut	I	Internal logic ensures that input signal does not float	none	none	VDD_EXT	Desc: MLB0 Differential Signal (+) Notes: No notes
PA_00	InOut	A	PullDown	none	none	VDD_EXT	Desc: PORTA Position 0 | EMAC0 Transmit Data 0 | SMC0 Address 21 Notes: No notes
PA_01	InOut	A	PullDown	none	none	VDD_EXT	Desc: PORTA Position 1 | EMAC0 Transmit Data 1 | SMC0 Address 20 Notes: No notes

Table 27. ADSP-SC58x/ADSP-2158x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Power Domain	Description and Notes
USB_XTAL	a		none	none	none		Desc: USB0/USB1 Crystal Notes: Services both USB0 and USB1
VDD_DMC	s	NA	none	none	none		Desc: DMC VDD Notes: No notes
VDD_EXT	s	NA	none	none	none		Desc: External Voltage Domain Notes: No notes
VDD_HADC	s	NA	none	none	none		Desc: HADC VDD Notes: No notes
VDD_INT	s	NA	none	none	none		Desc: Internal Voltage Domain Notes: No notes
VDD_PCIE	s	NA	none	none	none		Desc: PCIE Supply Voltage Notes: Connect to GND if not used[1]
VDD_PCIE_RX	s	NA	none	none	none		Desc: PCIE RX Supply Voltage Notes: Connect to GND if not used[1]
VDD_PCIE_TX	s	NA	none	none	none		Desc: PCIE TX Supply Voltage Notes: Connect to GND if not used[1]
VDD_RTC	s	NA	none	none	none		Desc: RTC VDD Notes: No notes
VDD_USB	s	NA	none	none	none		Desc: USB VDD Notes: Connect to VDD_EXT when USB is not used

[1] Guidance also applies to models that do not feature the associated hardware block. See Table 2 or Table 3 for further information.

Clock Related Operating Conditions

Table 29 describes the core clock, system clock, and peripheral clock timing requirements. The data presented in the table applies to all speed grades except where noted.

Table 29. Clock Operating Conditions

Parameter		Restriction	Min	Typ	Max	Unit
f_{CCLK}	Core Clock Frequency	$f_{CCLK} \geq f_{SYSCLK}$			450	MHz
f_{SYSCLK}	SYSCLK Frequency				225	MHz
f_{SCLK0}	SCLK0 Frequency[1]	$f_{SYSCLK} \geq f_{SCLK0}$	30		112.5	MHz
f_{SCLK1}	SCLK1 Frequency	$f_{SYSCLK} \geq f_{SCLK1}$			112.5	MHz
f_{DCLK}	LPDDR Clock Frequency				200	MHz
f_{DCLK}	DDR2 Clock Frequency				400	MHz
f_{DCLK}	DDR3 Clock Frequency				450	MHz
f_{OCLK}	Output Clock Frequency[2]				225	MHz
$f_{SYS\_CLKOUTJ}$	SYS_CLKOUT Period Jitter[3, 4]			±2		%
$f_{PCLKPROG}$	Programmed PPI Clock When Transmitting Data and Frame Sync				75	MHz
$f_{PCLKPROG}$	Programmed PPI Clock When Receiving Data or Frame Sync				45	MHz
$f_{PCLKEXT}$	External PPI Clock When Receiving Data and Frame Sync[5]	$f_{PCLKEXT} \leq f_{SCLK1}$			75	MHz
$f_{PCLKEXT}$	External PPI Clock Transmitting Data or Frame Sync[5, 6]	$f_{PCLKEXT} \leq f_{SCLK1}$			45	MHz
$f_{LCLKTPROG}$	Programmed Link Port Transmit Clock				150	MHz
$f_{LCLKREXT}$	External Link Port Receive Clock[5, 6]	$f_{LCLKEXT} \leq f_{CLKO8}$			150	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Transmitting Data and Frame Sync				56.25	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Receiving Data or Frame Sync				28.125	MHz
$f_{SPTCLKEXT}$	External SPT Clock When Receiving Data and Frame Sync[5, 6]	$f_{SPTCLKEXT} \leq f_{SCLK0}$			56.25	MHz
$f_{SPTCLKEXT}$	External SPT Clock Transmitting Data or Frame Sync[5, 6]	$f_{SPTCLKEXT} \leq f_{SCLK0}$			28.125	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Transmitting Data				75	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Receiving Data				75	MHz
$f_{SPICLKEXT}$	External SPI Clock When Receiving Data[5, 6]	$f_{SPICLKEXT} \leq f_{SCLK1}$			75	MHz
$f_{SPICLKEXT}$	External SPI Clock When Transmitting Data[5, 6]	$f_{SPICLKEXT} \leq f_{SCLK1}$			45	MHz
$f_{ACLKPROG}$	Programmed ACM Clock				56.25	MHz

[1] The minimum frequency for SCLK0 applies only when using the USB.
[2] f_{OCLK} must not exceed f_{SCLK0} when selected as SYS_CLKOUT.
[3] SYS_CLKOUT jitter is dependent on the application system design including pin switching activity, board layout, and the jitter characteristics of the SYS_CLKIN source. Due to the dependency on these factors, the measured jitter may be higher or lower than this typical specification for each end application.
[4] The typical value is the percentage of the SYS_CLKOUT period.
[5] The maximum achievable frequency for any peripheral in external clock mode is dependent on the ability to meet the setup and hold times in the ac timing specifications section for that peripheral.
[6] The peripheral external clock frequency must also be less than or equal to the f_{SCLK} (f_{SCLK0} or f_{SCLK1}) that clocks the peripheral.

HADC

HADC Electrical Characteristics

Table 37. HADC Electrical Characteristics

Parameter	Conditions	Typ	Unit
$I_{DD\_HADC\_IDLE}$	Current consumption on V_{DD_HADC}. HADC is powered on, but not converting.	2.0	mA
$I_{DD\_HADC\_ACTIVE}$	Current consumption on V_{DD_HADC} during a conversion.	2.5	mA
$I_{DD\_HADC\_POWERDOWN}$	Current consumption on V_{DD_HADC}. Analog circuitry of the HADC is powered down.	10	µA

HADC DC Accuracy

Table 38. HADC DC Accuracy[1]

Parameter	Typ	Unit[2]
Resolution	12	Bits
No Missing Codes (NMC)	10	Bits
Integral Nonlinearity (INL)	±2	LSB
Differential Nonlinearity (DNL)	±2	LSB
Offset Error	±8	LSB
Offset Error Matching	±10	LSB
Gain Error	±4	LSB
Gain Error Matching	±4	LSB

[1] See the Operating Conditions section for the HADC0_VINx specification.
[2] LSB = HADC0_VREFP ÷ 4096.

HADC Timing Specifications

Table 39. HADC Timing Specifications

Parameter	Typ	Max	Unit
Conversion Time	$20 \times T_{SAMPLE}$		µs
Throughput Range		1	MSPS
T_{WAKEUP}		100	µs

TMU

TMU Characteristics

Table 40. TMU Characteristics

Parameter	Typ	Unit
Resolution	1	°C
Accuracy	±6	°C

Asynchronous Flash Read

Table 46 and Figure 13 show asynchronous flash memory read timing, related to the SMC.

Table 46. Asynchronous Flash Read

Parameter		Min	Max	Unit
Switching Characteristics				
t_{AMSADV}	SMC0_Ax (Address)/$\overline{\text{SMC0\_AMSx}}$ Assertion Before SMC0_NORDV Low[1]	PREST × t_{SCLK0} – 2		ns
t_{WADV}	SMC0_NORDV Active Low Width[2]	RST × t_{SCLK0} – 2		ns
$t_{DADVARE}$	$\overline{\text{SMC0\_ARE}}$ Low Delay From SMC0_NORDV High[3]	PREAT × t_{SCLK0} – 2		ns
t_{HARE}	Output[4] Hold After $\overline{\text{SMC0\_ARE}}$ High[5]	RHT × t_{SCLK0} – 2		ns
t_{WARE}[6]	$\overline{\text{SMC0\_ARE}}$ Active Low Width[7]	RAT × t_{SCLK0} – 2		ns

[1] PREST value set using the SMC_BxETIM.PREST bits.
[2] RST value set using the SMC_BxTIM.RST bits.
[3] PREAT value set using the SMC_BxETIM.PREAT bits.
[4] Output signals are SMC0_Ax, $\overline{\text{SMC0\_AMS}}$, $\overline{\text{SMC0\_AOE}}$.
[5] RHT value set using the SMC_BxTIM.RHT bits.
[6] SMC0_BxCTL.ARDYEN bit = 0.
[7] RAT value set using the SMC_BxTIM.RAT bits.

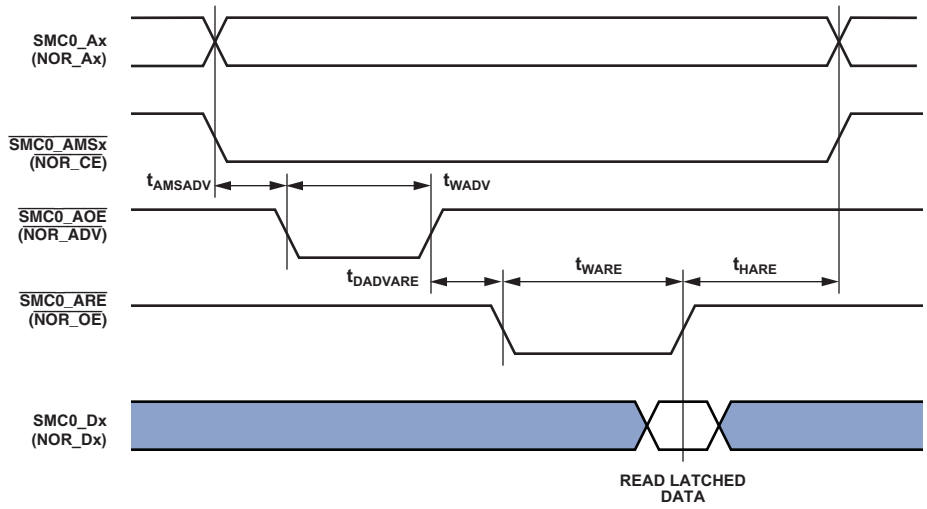

Figure 13. Asynchronous Flash Read

Mobile DDR SDRAM Write Cycle Timing

Table 56 and Figure 22 show mobile DDR SDRAM write cycle timing, related to the DMC.

Table 56. Mobile DDR SDRAM Write Cycle Timing, V_{DD_DMCx} Nominal 1.8 V[1]

Parameter		200 MHz[2] Min	200 MHz[2] Max	Unit
Switching Characteristics				
t_{DQSS}[3]	DMCx_DQS Latching Rising Transitions to Associated Clock Edges	0.75	1.25	t_{CK}
t_{DS}	Last Data Valid to DMCx_DQS Delay (Slew > 1 V/ns)	0.48		ns
t_{DH}	DMCx_DQS to First Data Invalid Delay (Slew > 1 V/ns)	0.48		ns
t_{DSS}	DMCx_DQS Falling Edge to Clock Setup Time	0.2		t_{CK}
t_{DSH}	DMCx_DQS Falling Edge Hold Time From DMCx_CK	0.2		t_{CK}
t_{DQSH}	DMCx_DQS Input High Pulse Width	0.4		t_{CK}
t_{DQSL}	DMCx_DQS Input Low Pulse Width	0.4		t_{CK}
t_{WPRE}	Write Preamble	0.25		t_{CK}
t_{WPST}	Write Postamble	0.4		t_{CK}
t_{IPW}	Address and Control Output Pulse Width	2.3		ns
t_{DIPW}	DMCx_DQ and DMCx_DM Output Pulse Width	1.8		ns

[1] Specifications apply to both DMC0 and DMC1.
[2] To ensure proper operation of LPDDR, all the LPDDR guidelines must be strictly followed. See "Interfacing DDR3/DDR2/LPDDR Memory to ADSP-SC5xx/215xx Processors" (EE-387).
[3] Write command to first DMCx_DQS delay = WL × t_{CK} + t_{DQSS}.

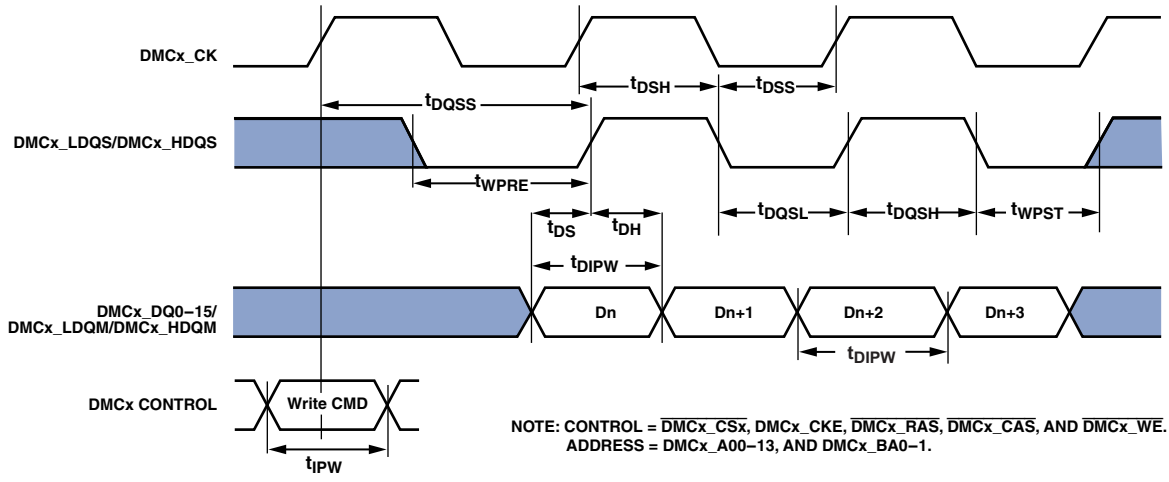

Figure 22. Mobile DDR SDRAM Controller Output AC Timing

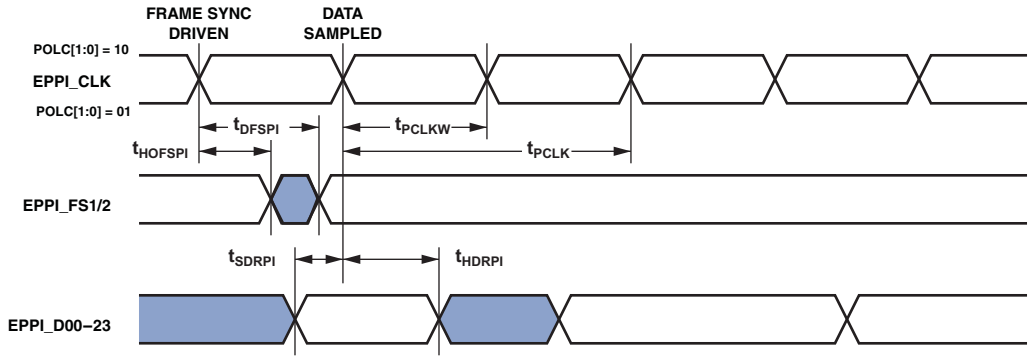

Figure 26. EPPI Internal Clock GP Receive Mode with Internal Frame Sync Timing

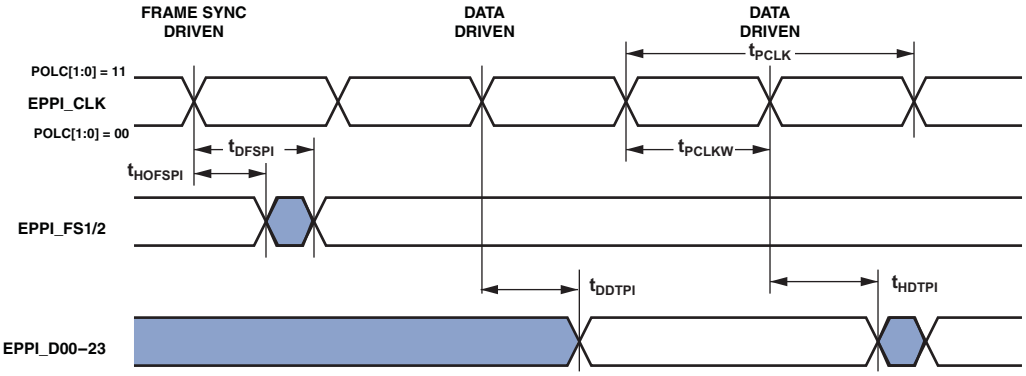

Figure 27. EPPI Internal Clock GP Transmit Mode with Internal Frame Sync Timing

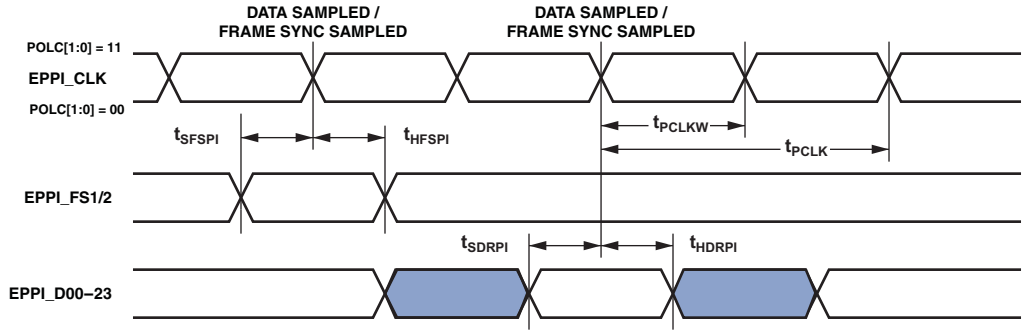

Figure 28. EPPI Internal Clock GP Receive Mode with External Frame Sync Timing

SPI Port—Slave Timing

Table 72 and Figure 44 describe SPI port slave operations. Note that

- In dual-mode data transmit, the SPIx_MOSI signal is also an output.
- In quad-mode data transmit, the SPIx_MOSI, SPIx_D2, and SPIx_D3 signals are also outputs.
- In dual-mode data receive, the SPIx_MISO signal is also an input.
- In quad-mode data receive, the SPIx_MISO, SPIx_D2, and SPIx_D3 signals are also inputs.
- In SPI slave mode, the SPI clock is supplied externally and is called $f_{SPICLKEXT}$:

$$t_{SPICLKEXT} = \frac{1}{f_{SPICLKEXT}}$$

- Quad mode is supported by SPI2 only.
- CPHA is a configuration bit in the SPI_CTL register.

Table 72. SPI Port—Slave Timing[1]

Parameter		Min	Max	Unit
Timing Requirements				
t_{SPICHS}	SPIx_CLK High Period[2]	$0.5 \times t_{SPICLKEXT} - 1$		ns
t_{SPICLS}	SPIx_CLK Low Period[2]	$0.5 \times t_{SPICLKEXT} - 1$		ns
t_{SPICLK}	SPIx_CLK Period[2]	$t_{SPICLKEXT} - 1$		ns
t_{HDS}	Last SPIx_CLK Edge to $\overline{\text{SPIx\_SS}}$ Not Asserted	5		ns
t_{SPITDS}	Sequential Transfer Delay	$t_{SPICLK} - 1$		ns
t_{SDSCI}	$\overline{\text{SPIx\_SS}}$ Assertion to First SPIx_CLK Edge	10.5		ns
t_{SSPID}	Data Input Valid to SPIx_CLK Edge (Data Input Setup)	2		ns
t_{HSPID}	SPIx_CLK Sampling Edge to Data Input Invalid	1.6		ns
Switching Characteristics				
t_{DSOE}	$\overline{\text{SPIx\_SS}}$ Assertion to Data Out Active	0	14	ns
t_{DSDHI}	$\overline{\text{SPIx\_SS}}$ Deassertion to Data High Impedance	0	12.5	ns
t_{DDSPID}	SPIx_CLK Edge to Data Out Valid (Data Out Delay)		14	ns
t_{HDSPID}	SPIx_CLK Edge to Data Out Invalid (Data Out Hold)	0		ns

[1] All specifications apply to all three SPIs.
[2] This specification indicates the minimum instantaneous width or period that can be tolerated due to duty cycle variation or jitter on the external SPIx_CLK. For the external SPIx_CLK ideal maximum frequency see the $f_{SPICLKTEXT}$ specification in Table 29.

SPI Port—SPIx_RDY Slave Timing

SPIx_RDY is used to provide flow control. CPOL, CPHA, and FCCH are configuration bits in the SPIx_CTL register.

Table 73. SPI Port—SPIx_RDY Slave Timing[1]

Parameter		Conditions	Min	Max	Unit
Switching Characteristic					
$t_{DSPISCKRDYS}$	SPIx_RDY Deassertion from Last Valid Input SPIx_CLK Edge	FCCH = 0	$3 \times t_{SCLK1}$	$4 \times t_{SCLK1} + 10$	ns
		FCCH = 1	$4 \times t_{SCLK1}$	$5 \times t_{SCLK1} + 10$	ns

[1] All specifications apply to all three SPIs.

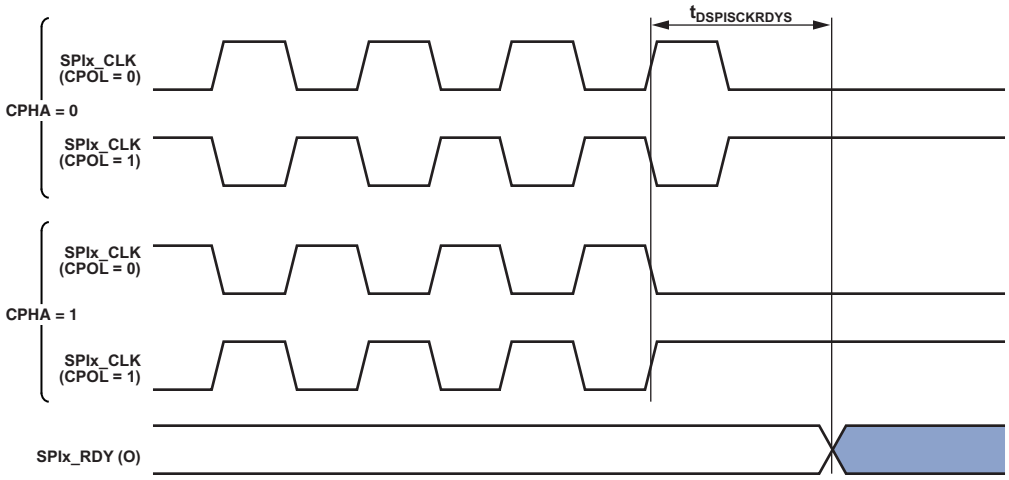

Figure 45. SPIx_RDY Deassertion from Valid Input SPIx_CLK Edge in Slave Mode

10/100 EMAC Timing (ETH0 and ETH1)

Table 88 through Table 90 and Figure 59 through Figure 61 describe the 10/100 EMAC operations.

Table 88. 10/100 EMAC Timing—RMII Receive Signal[1]

Parameter[2]		Min	Max	Unit
Timing Requirements				
$t_{REFCLKF}$	ETHx_REFCLK Frequency (f_{SCLK0} = SCLK0 Frequency)		50 + 1%	MHz
$t_{REFCLKW}$	ETHx_REFCLK Width ($t_{REFCLKF}$ = ETHx_REFCLK Period)	$t_{REFCLKF} \times 35\%$	$t_{REFCLKF} \times 65\%$	ns
$t_{REFCLKIS}$	Rx Input Valid to RMII ETHx_REFCLK Rising Edge (Data In Setup)	1.75		ns
$t_{REFCLKIH}$	RMII ETHx_REFCLK Rising Edge to Rx Input Invalid (Data In Hold)	1.6		ns

[1] These specifications apply to ETH0 and ETH1.
[2] RMII inputs synchronous to RMII ETHx_REFCLK are ETHx_RXD1–0, RMII ETHx_CRS, and ERxER.

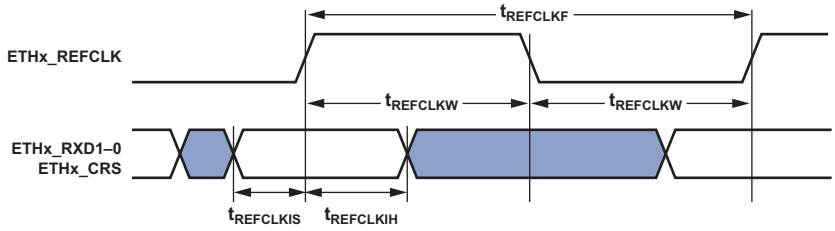

Figure 59. 10/100 EMAC Controller Timing—RMII Receive Signal

Table 89. 10/100 EMAC Timing—RMII Transmit Signal[1]

Parameter[2]		Min	Max	Unit
Switching Characteristics				
$t_{REFCLKOV}$	RMII ETHx_REFCLK Rising Edge to Transmit Output Valid (Data Out Valid)		11.9	ns
$t_{REFCLKOH}$	RMII ETHx_REFCLK Rising Edge to Transmit Output Invalid (Data Out Hold)	2		ns

[1] These specifications apply to ETH0 and ETH1.
[2] RMII outputs synchronous to RMII ETHx_REFCLK are ETHx_TXD1–0.

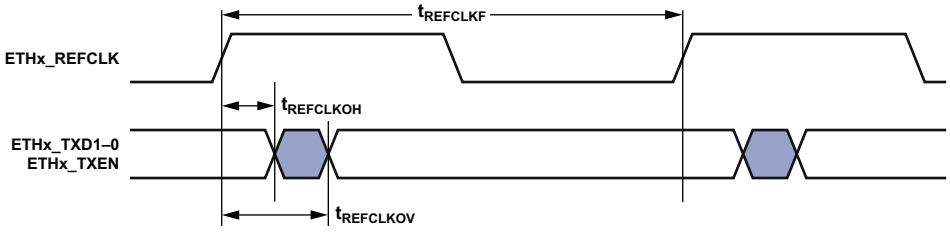

Figure 60. 10/100 EMAC Controller Timing—RMII Transmit Signal

Sinus Cardinalis (SINC) Filter Timing

The programmed SINC filter clock ($f_{SINCLKPROG}$) frequency in MHz is set by the following equation where MDIV is a field in the CLK control register that can be set from 4 to 63:

$$f_{SINCLKPROG} = \frac{f_{SCLK}}{MDIV}$$

$$t_{SINCLKPROG} = \frac{1}{f_{SINCLKPROG}}$$

Table 92. SINC Timing

Parameter		Min	Max	Unit
Timing Requirements				
t_{SSINC}	SINC0_Dx Setup Before SINC0_CLKx Rise	13.5		ns
t_{HSINC}	SINC0_Dx Hold After SINC0_CLKx Rise	0		ns
Switching Characteristics				
t_{SINCLK}	SINC0_CLKx Period[1]	$t_{SINCLKPROG} - 2.5$		ns
$t_{SINCLKW}$	SINC0_CLKx Width[1]	$0.5 \times t_{SINCLKPROG} - 2.5$		ns

[1] See Table 29 for details on the minimum period that may be programmed for $t_{SINCLKPROG}$.

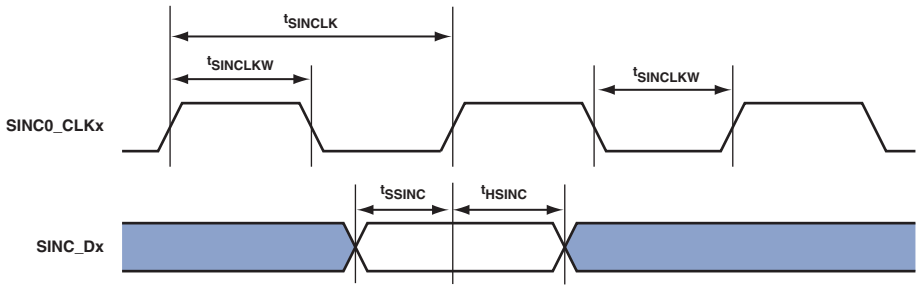

Figure 63. SINC Timing

CONFIGURATION OF THE 529-BALL CSP_BGA

Figure 99 shows an overview of signal placement on the 529-ball CSP_BGA.

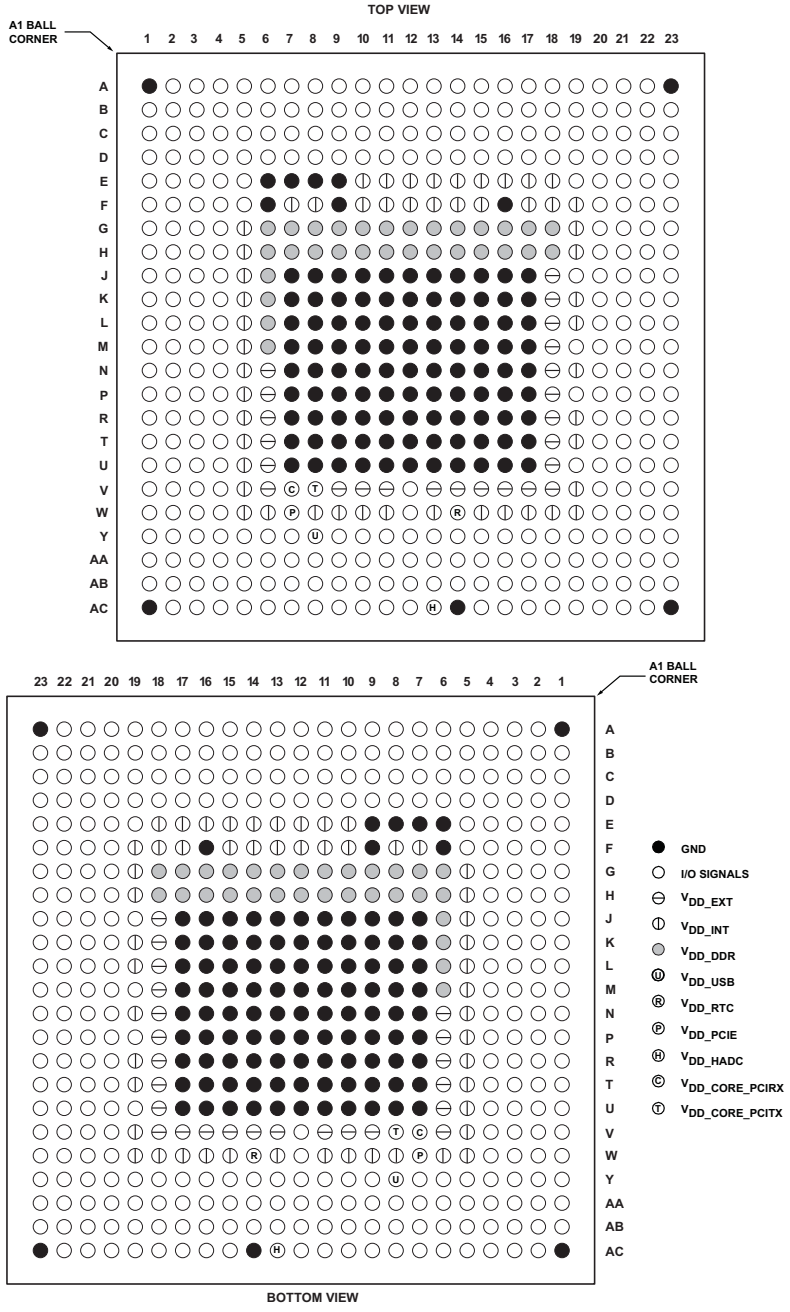

Figure 99. 529-Ball CSP_BGA Configuration